CEP740N/CEB740N
CEF740N

N-Channel Enhancement Mode Field Effect Transistor

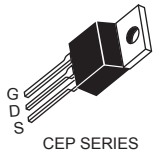
PRELIMINARY

FEATURES

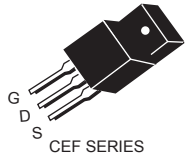
Type	V_{DSS}	$R_{DS(ON)}$	I_D	@V_{GS}
CEP740N	400V	550mΩ	10A	10V
CEB740N	400V	550mΩ	10A	10V
CEF740N	400V	550mΩ	10A [e]	10V

- Super high dense cell design for extremely low $R_{DS(ON)}$.
- High power and current handing capability.
- Lead free product is acquired.

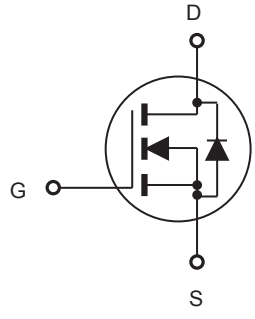
CEB SERIES
TO-263(DD-PAK)



CEP SERIES
TO-220



CEF SERIES
TO-220F



ABSOLUTE MAXIMUM RATINGS T_C = 25°C unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V_{DS}	400		V
Gate-Source Voltage	V_{GS}	±30		V
Drain Current-Continuous	I_D	10	10 [e]	A
Drain Current-Pulsed [a]	I_{DM} [f]	40	40 [e]	A
Maximum Power Dissipation @ T_C = 25°C	P_D	125	40	W
- Derate above 25°C		1	0.32	W/°C
Single Pulsed Avalanche Energy [d]	E_{AS}	458	458	mJ
Single Pulsed Avalanche Current [d]	I_{AS}	10	10	A
Operating and Store Temperature Range	T_J,T_{stg}	-55 to 150		°C

Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	RθJC	1.0	3.1	°C/W
Thermal Resistance, Junction-to-Ambient	RθJA	62.5	65	°C/W

This is preliminary information on a new product in development now .
Details are subject to change without notice .

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Electrical Characteristics T_C = 25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS} = 0V, I_D = 250μA	400			V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 400V, V_{GS} = 0V			50	μA
Gate Body Leakage Current, Forward	I_{GSSF}	V_{GS} = 30V, V_{DS} = 0V			100	nA
Gate Body Leakage Current, Reverse	I_{GSSR}	V_{GS} = -30V, V_{DS} = 0V			-100	nA
On Characteristics [b]						
Gate Threshold Voltage	$V_{GS(th)}$	V_{GS} = V_{DS}, I_D = 250μA	2		4	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	V_{GS} = 10V, I_D = 6A		450	550	mΩ
Forward Transconductance	g_{FS}	V_{DS} = 50V, I_D = 6A		6		S
Dynamic Characteristics [c]						
Input Capacitance	C_{iss}	V_{DS} = 25V, V_{GS} = 0V, f = 1.0 MHz		1400		pF
Output Capacitance	C_{oss}			180		pF
Reverse Transfer Capacitance	C_{rss}			65		pF
Switching Characteristics [c]						
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 200V, I_D = 10A, V_{GS} = 10V, R_{GEN} = 9.1Ω		25	50	ns
Turn-On Rise Time	t_r			30	60	ns
Turn-Off Delay Time	$t_{d(off)}$			175	350	ns
Turn-Off Fall Time	t_f			33	66	ns
Total Gate Charge	Q_g	V_{DS} = 320V, I_D = 10A, V_{GS} = 10V		60	78	nC
Gate-Source Charge	Q_{gs}			10		nC
Gate-Drain Charge	Q_{gd}			30		nC
Drain-Source Diode Characteristics and Maximun Ratings						
Drain-Source Diode Forward Current	I_S [g]				10	A
Drain-Source Diode Forward Voltage [b]	V_{SD}	V_{GS} = 0V, I_S = 10A [h]			2	V

Notes :
a.Repetitive Rating : Pulse width limited by maximum junction temperature .
b.Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2% .
c.Guaranteed by design, not subject to production testing.
d.L =9.16mH, I_{AS} =10A, V_{DD} = 50V, R_G = 25Ω, Starting T_J = 25°C .
e.Limited only by maximum temperature allowed .
f .Pulse width limited by safe operating area .
g.Full package $I_{S(max)}$ = 5.5A .
h.Full package V_{SD} test condition I_S = 5.5A .

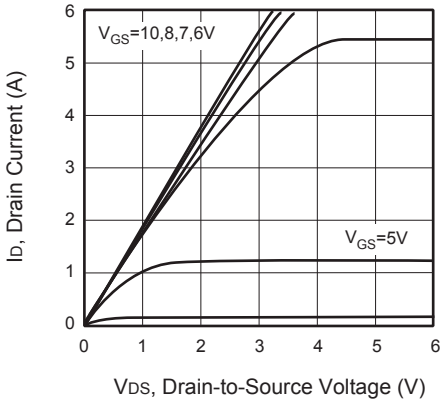

Figure 1. Output Characteristics

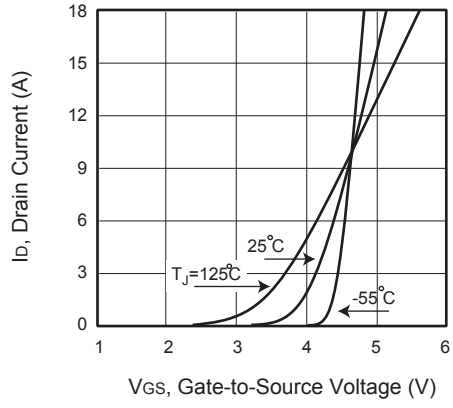

Figure 2. Transfer Characteristics

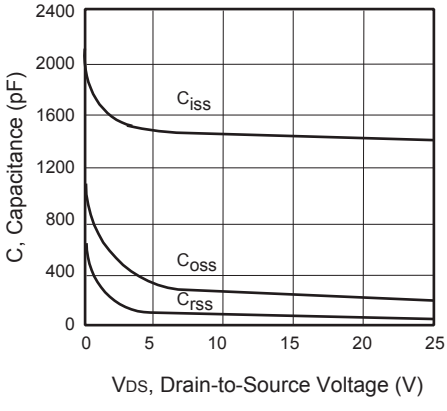

Figure 3. Capacitance

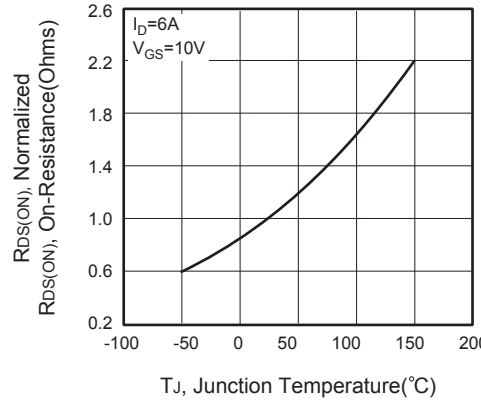

Figure 4. On-Resistance Variation with Temperature

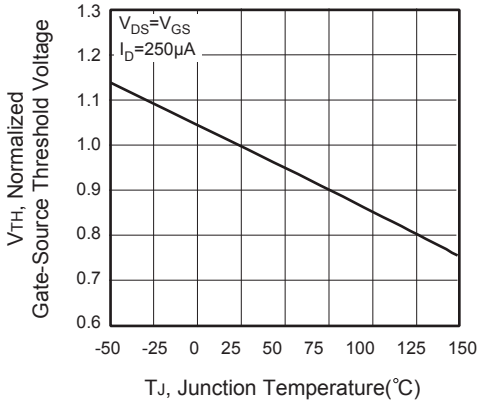

Figure 5. Gate Threshold Variation with Temperature

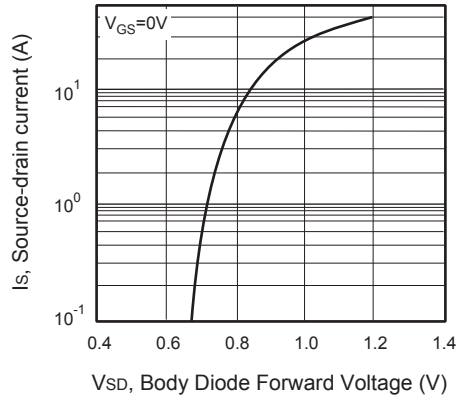

Figure 6. Body Diode Forward Voltage Variation with Source Current

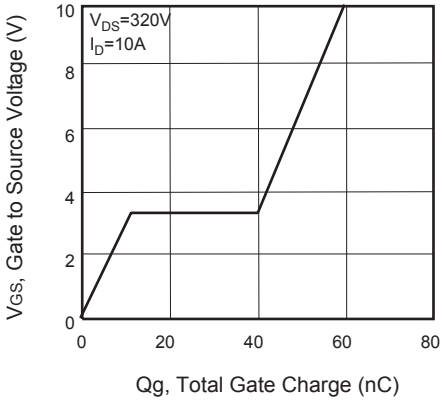

Figure 7. Gate Charge

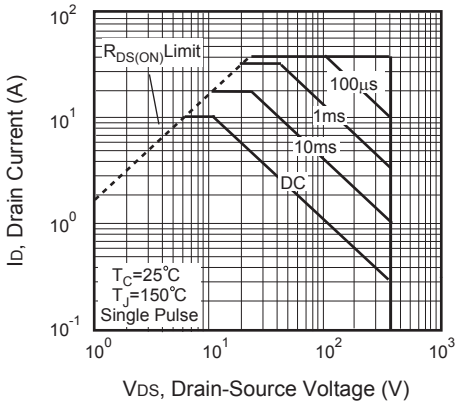

Figure 8. Maximum Safe Operating Area

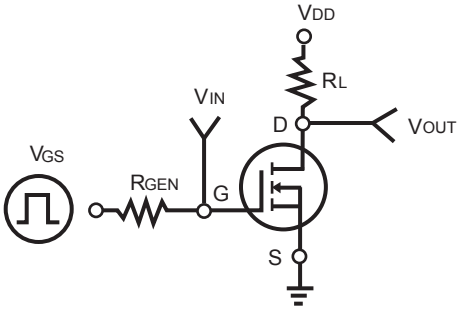

Figure 9. Switching Test Circuit

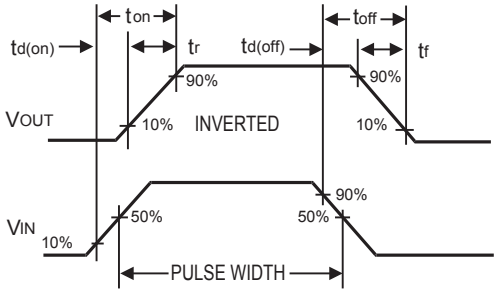

Figure 10. Switching Waveforms

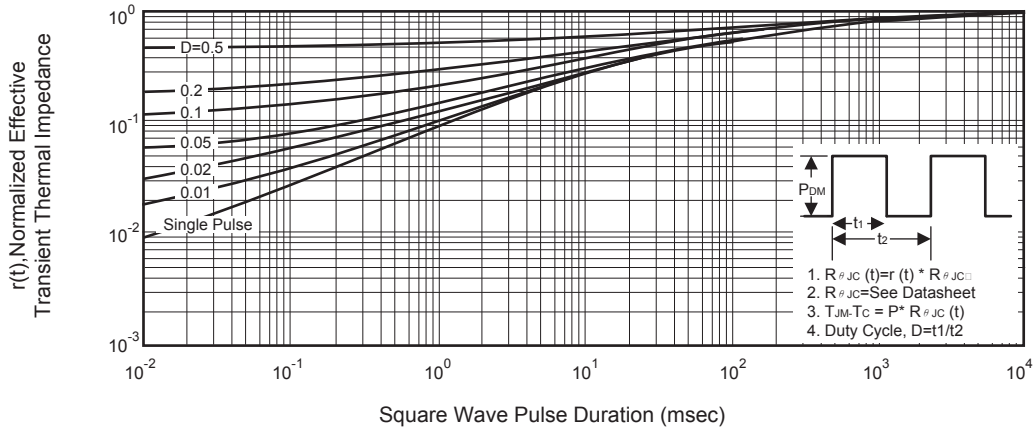

Figure 11. Normalized Thermal Transient Impedance Curve